

# Supply Chain Explorer

By the Emerging Technology Observatory

This is an export from the ETO Supply Chain Explorer, available at: <https://chipexplorer.eto.tech> You can see the web version of this content at <https://chipexplorer.eto.tech/?filter-choose=input-resource&input-resource=N95>.

## Ceramic packages

Protective ceramic packages, plastic substrates, or encapsulant resins may be bonded to a chip during the packaging process.

### Country provision

- China (mainland)
- Germany
- Japan
- South Korea
- United States

### Notable supplier companies

- Alent - United Kingdom
- Amkor - United States
- BASF - Germany
- Henkel - Germany
- Hitachi - Japan
- Kyocera - Japan
- LG - South Korea
- Mitsui High-Tec - Japan
- NGK - Japan
- QP Technologies - United States
- Sumitomo - Japan
- Tanaka - Japan
- Toray - Japan
- Yixing - China (mainland)
- Zhongwei - China (mainland)